

# SOP022-1

land grid array package; 274 lands

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LGA274
<b>Package type industry code</b>	LGA274
<b>Package style descriptive code</b>	LGA (land grid array package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	16-4-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	32.85	-	33	33.15	mm
E	package width	32.85	-	33	33.15	mm
A	seated height	3.18	-	3.38	3.58	mm
e	nominal pitch	-	-	1.6	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	274	-	



## 2. Package outline

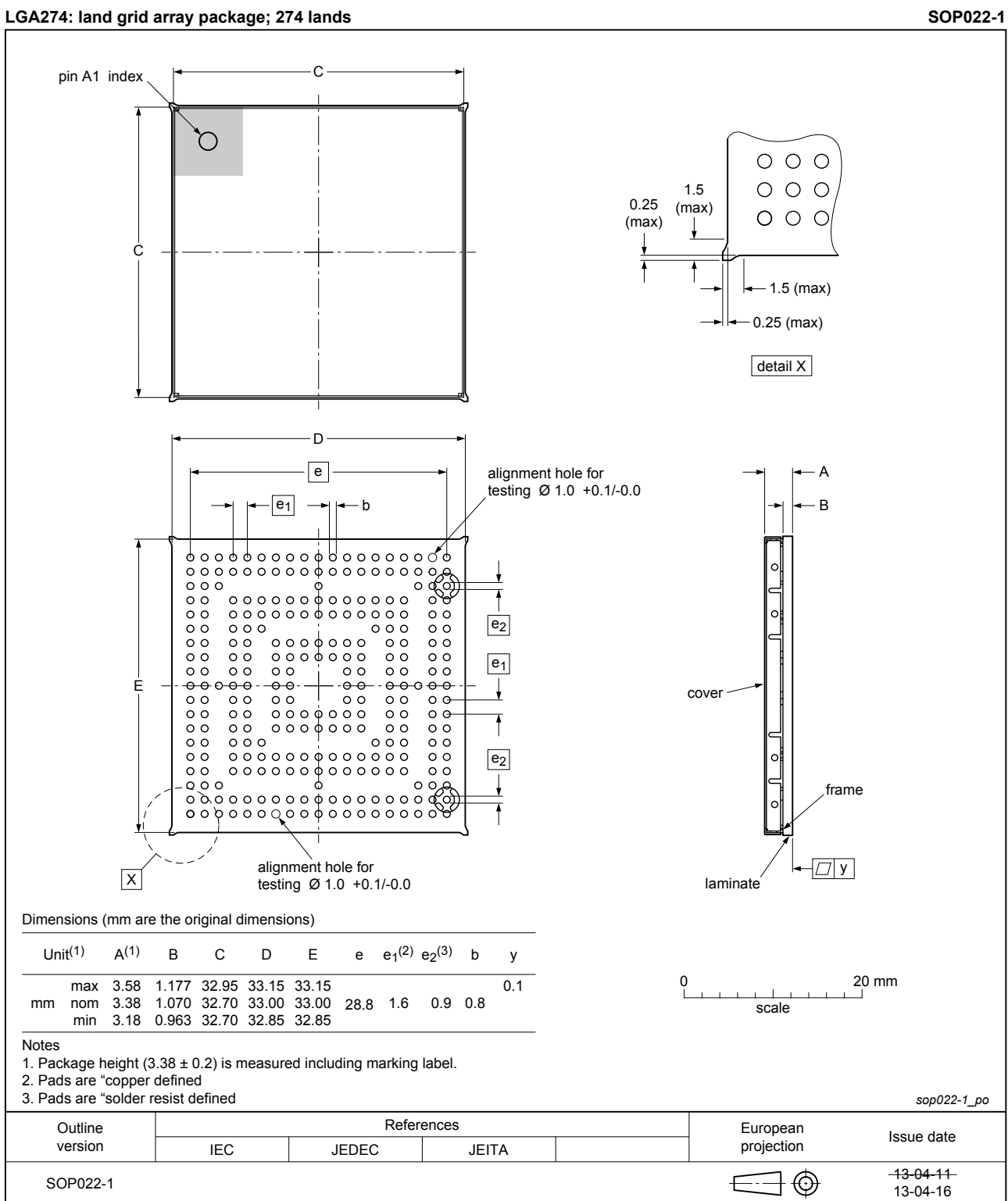
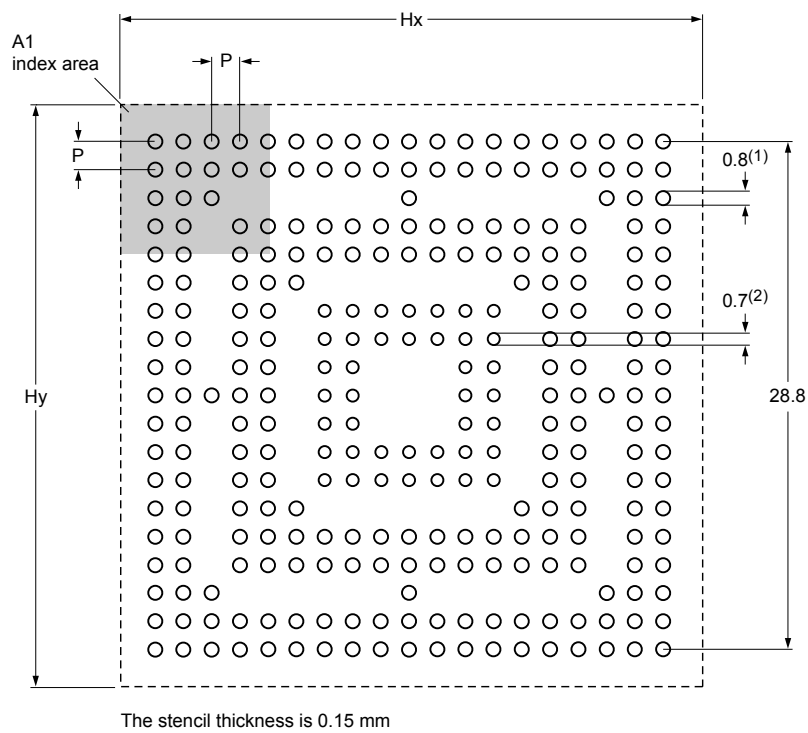


Fig. 1. Package outline LGA274 (SOP022-1)

### 3. Soldering

Footprint information for reflow soldering of LGA274 package

SOP022-1



----- occupied area

Dimensions in mm

P	Hx	Hy
1.6	33.0	33.0

sop022-1\_fr

Fig. 2. Reflow soldering footprint for LGA274 (SOP022-1)

## 4. Legal information

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Date of release: 8 February 2016

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